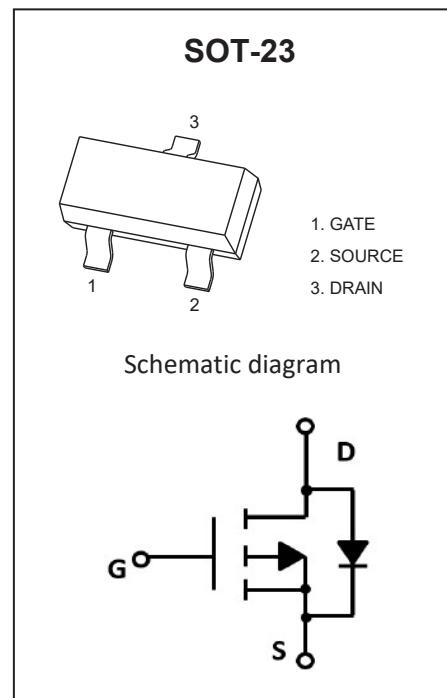


## P-Channel Enhancement Mode Field Effect Transistor

### Product Summary

V <sub>(BR)DSS</sub>	R <sub>D(on)TYP</sub>	I <sub>D</sub>
-12V	50 mΩ@4.5V	-4.3A
	85 mΩ@2.5V	
	30mΩ@1.8V	



### General Description

- Trench Power LV MOSFET technology
- Low R<sub>D(on)</sub>
- Low Gate Charge

### Applications

- PWM applications
- Power management
- Load switch

### ■ Absolute Maximum Ratings (T<sub>A</sub>=25°C unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		V <sub>DS</sub>	-12	V
Gate-source Voltage		V <sub>GS</sub>	±10	V
Drain Current	T <sub>A</sub> =25°C	I <sub>D</sub>	-4.3	A
	T <sub>A</sub> =70°C		-3	
Pulsed Drain Current <sup>A</sup>		I <sub>DM</sub>	-15	A
Total Power Dissipation	T <sub>A</sub> =25°C	P <sub>D</sub>	1	W
	T <sub>A</sub> =70°C		0.64	W
Thermal Resistance Junction-to-Ambient <sup>B</sup>		R <sub>θJA</sub>	125	°C / W
Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55~+150	°C

### ■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
6401	F2	1F/F****	3000	45000	180000	7" reel

**■ Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)**

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA	-12			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-19V, V <sub>GS</sub> =0V			-1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±10V, V <sub>DS</sub> =0V			±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-0.4	-0.62	-0.95	V
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-3.8A		36	50	mΩ
		V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-3.0A		55	85	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =-3.8A, V <sub>GS</sub> =0V			-1.2	V
<b>Dynamic Parameters</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =-10V, V <sub>GS</sub> =0V, f=1MHZ		606		pF
Output Capacitance	C <sub>oss</sub>			114		
Reverse Transfer Capacitance	C <sub>rss</sub>			103		
<b>Switching Parameters</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> =-10V, V <sub>DS</sub> =-10V, I <sub>D</sub> =-3.8A		8.48		nC
Gate-Source Charge	Q <sub>gs</sub>			1.54		
Gate-Drain Charge	Q <sub>gd</sub>			2.61		
Turn-on Delay Time	t <sub>D(on)</sub>	V <sub>GS</sub> =-4.5V, V <sub>DS</sub> =-10V, I <sub>D</sub> =-3.8A R <sub>GEN</sub> =3Ω		5.8		
Turn-on Rise Time	t <sub>r</sub>			34.8		
Turn-off Delay Time	t <sub>D(off)</sub>			51.4		
Turn-off fall Time	t <sub>f</sub>			52		

A. Pulse Test: Pulse Width≤300us, Duty cycle ≤2%.

B. R<sub>θJA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. R<sub>θJC</sub> is guaranteed by design, while R<sub>θJA</sub> is determined by the board design. The maximum rating presented here is based on mounting on a 1 in 2 pad of 2oz copper.

## ■ Typical Performance Characteristics

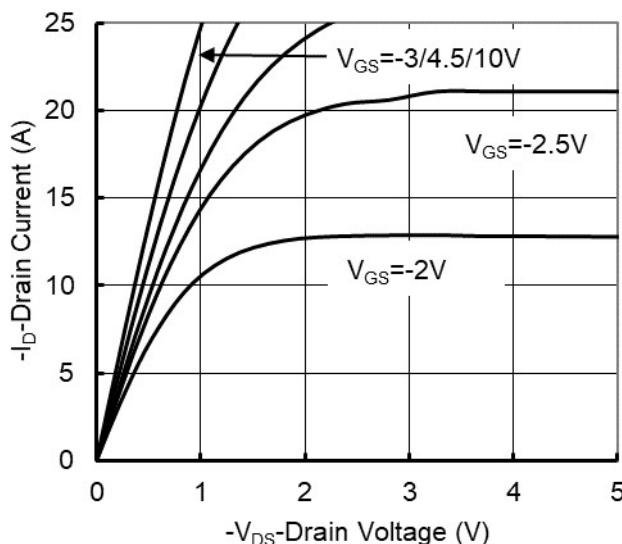


Figure 1. Output Characteristics

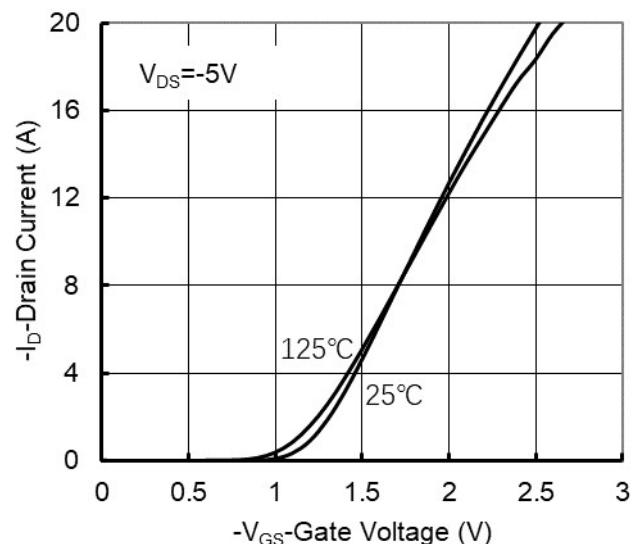


Figure 2. Transfer Characteristics

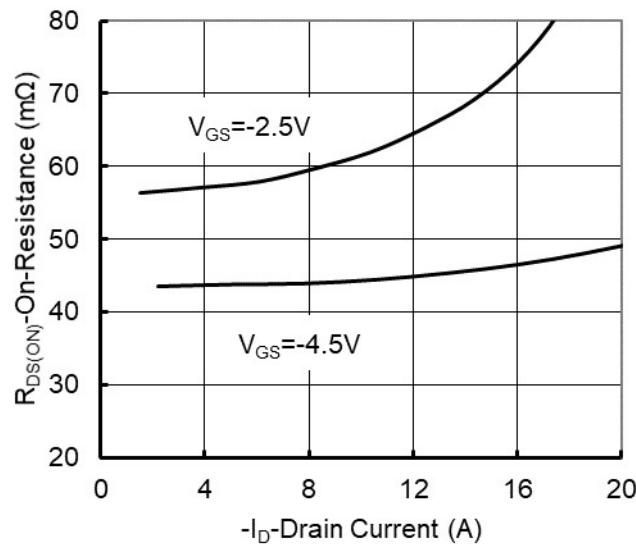


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

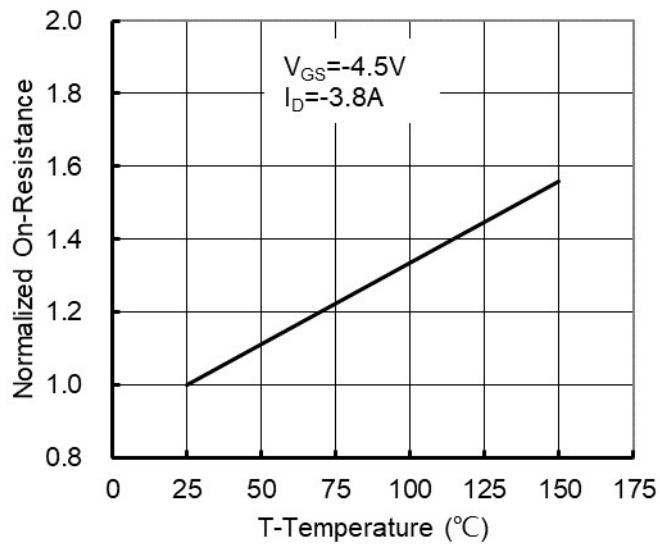


Figure 4: On-Resistance vs. Junction Temperature

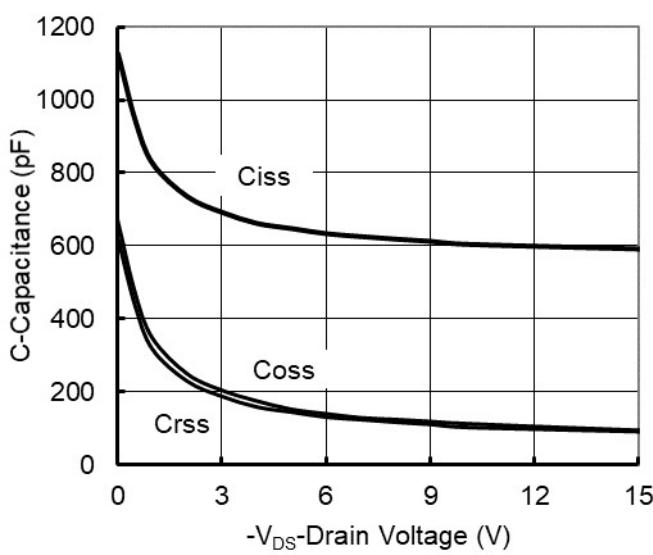


Figure 5. Capacitance Characteristics

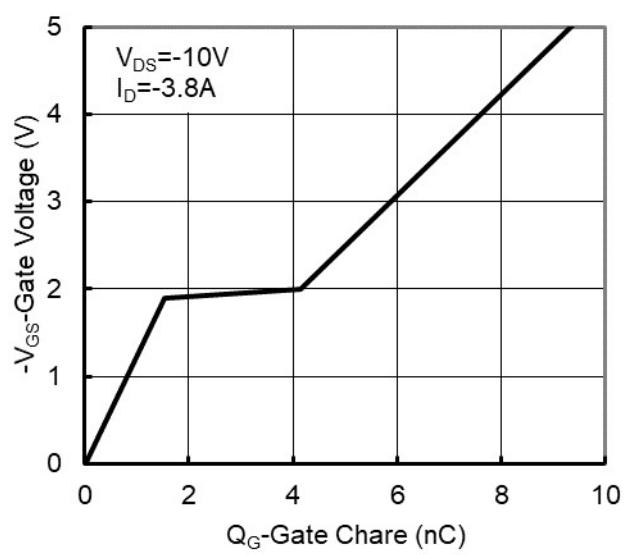
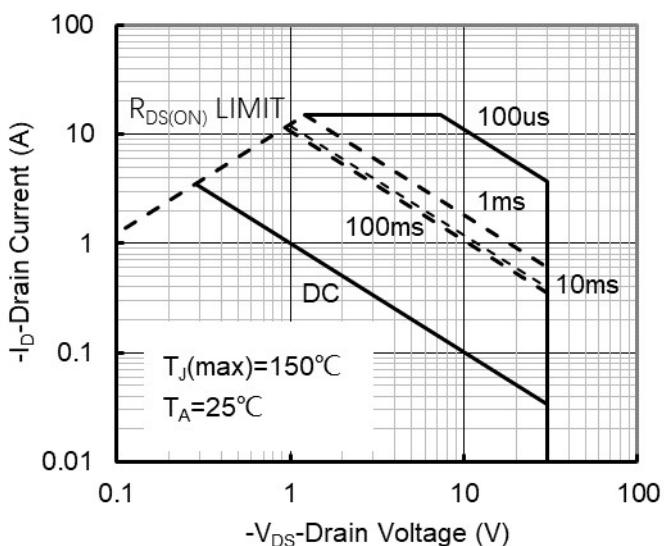
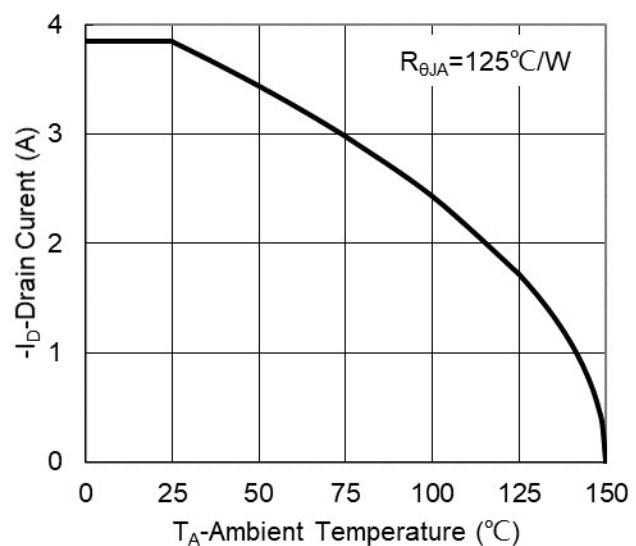
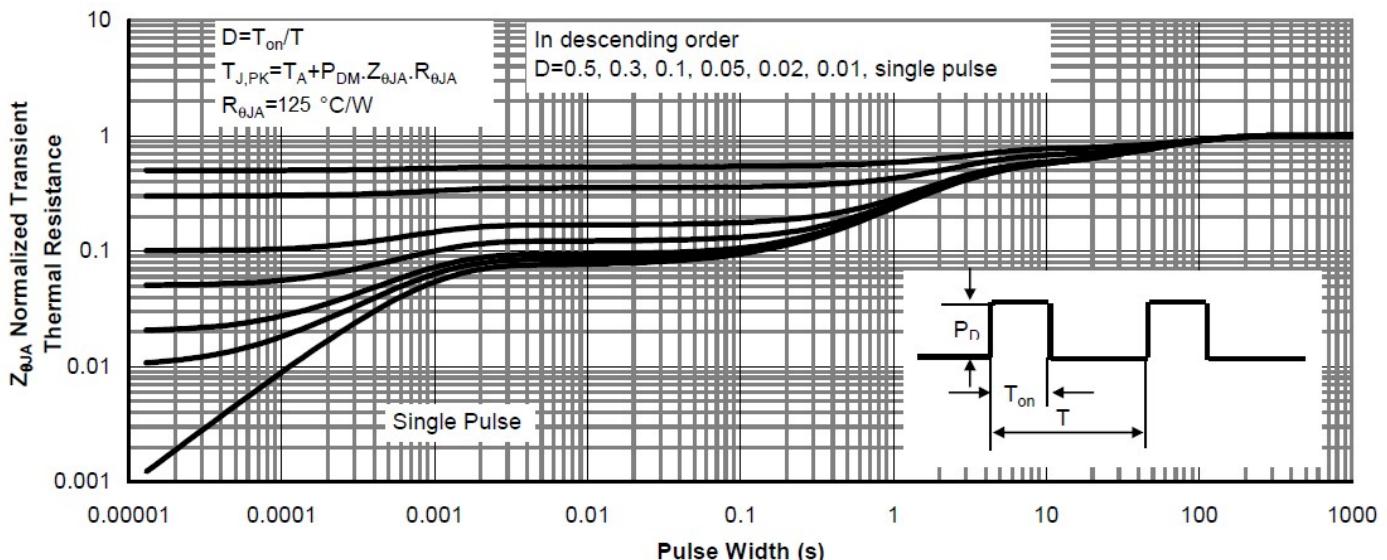
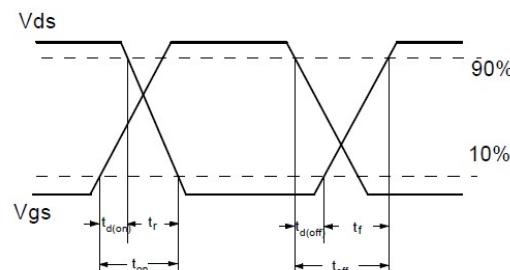
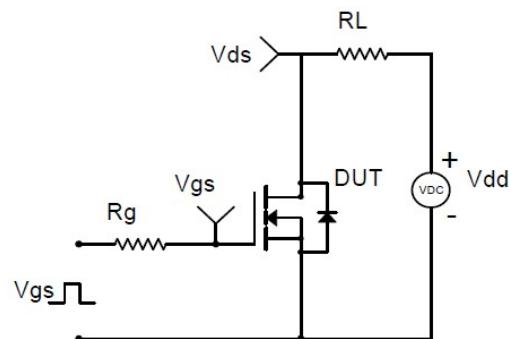
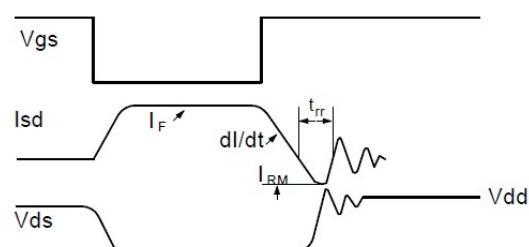
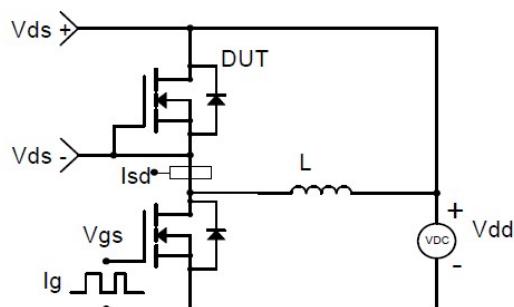
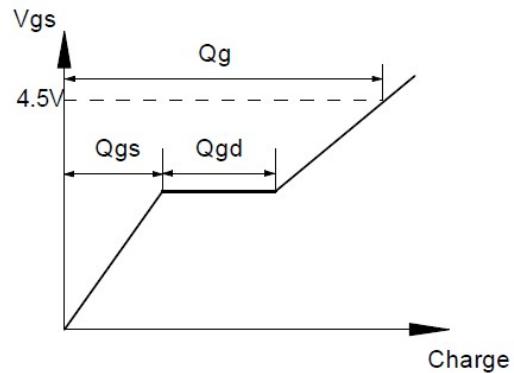
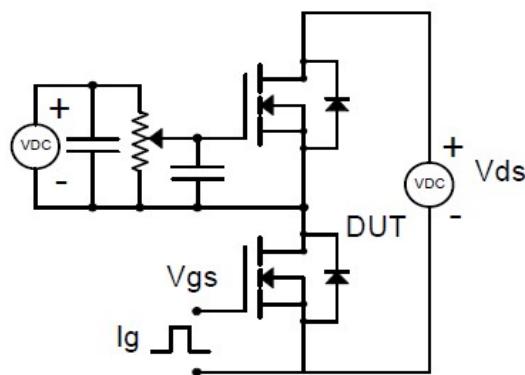
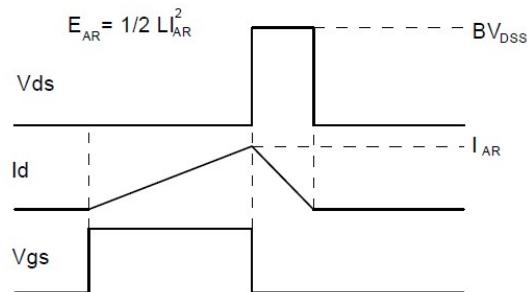
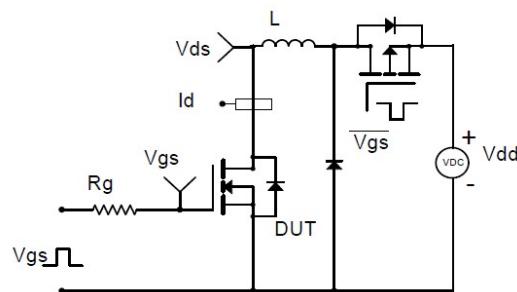
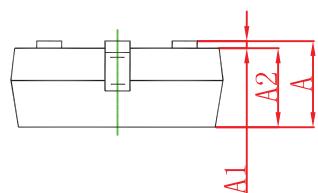
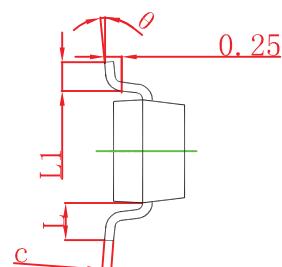
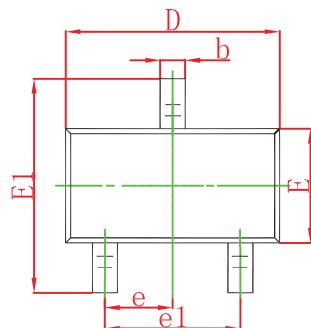


Figure 6. Gate Charge

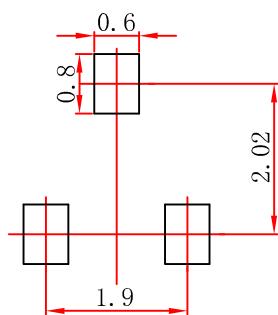

**Figure7. Safe Operation Area**

**Figure8. Maximum Continuous Drain Current vs Ambient Temperature**

**Figure9. Normalized Maximum Transient Thermal Impedance**


**Resistive Switching Test Circuit & Waveforms**

**Diode Recovery Test Circuit & Waveforms**

**Gate Charge Test Circuit & Waveform**

**Unclamped Inductive Switching (UIS) Test Circuit & Waveforms**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

## SOT-23 Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.05\text{mm}$ .
3. The pad layout is for reference purposes only.